

NCE N-Channel Super Trench II Power MOSFET

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

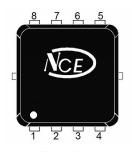
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

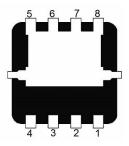
General Features

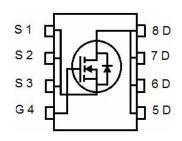
- V_{DS} =30V,I_D =70A
 R_{DS(ON)}=1.75mΩ (typical) @ V_{GS}=10V
 R_{DS(ON)}=3.0mΩ (typical) @ V_{GS}=4.5V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

DFN 3.3X3.3







Top View Bo

Bottom View Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP020N30QU	NCEP020N30QU	DFN3.3X3.3-8L	_	_	_

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	70	Α
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	55	Α
Pulsed Drain Current	I _{DM}	280	Α
Maximum Power Dissipation	P _D	55	W
Derating factor		0.44	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	352	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	Rejc	2.3	°C/W
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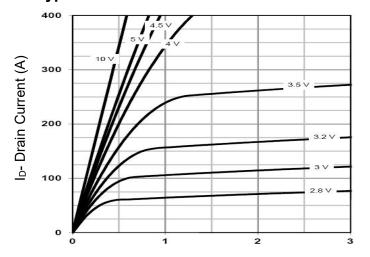
Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V_{DS} = V_{GS} , I_D =250 μ A	1.0	1.6	2.0	V
Drain-Source On-State Resistance	D	V_{GS} =10V, I_D =35A	-	1.75	2.0	mΩ
Dialii-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =35A	-	3.0	4.0	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =35A		65	-	S
Dynamic Characteristics (Note4)			·			
Input Capacitance	C _{lss}	\/ -45\/\/ -0\/	-	2400	-	PF
Output Capacitance	Coss	V_{DS} =15V, V_{GS} =0V, F=1.0MHz	-	1700	-	PF
Reverse Transfer Capacitance	Crss	r-1.0WHZ	-	120	-	PF
Switching Characteristics (Note 4)			·			
Turn-on Delay Time	t _{d(on)}		-	5.0	-	nS
Turn-on Rise Time	t _r	V_{DD} =15V, I_D =35A	-	7.0	-	nS
Turn-Off Delay Time	t _{d(off)}	$V_{GS}\text{=}10V, R_{G}\text{=}1.6\Omega$	-	27.0	-	nS
Turn-Off Fall Time	t _f		-	5.0	-	nS
Total Gate Charge	Qg)/ 45)/ OF A	-	40.5	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =35A,	-	6.5		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	7		nC
Drain-Source Diode Characteristics					-	
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =35A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	70	Α
Reverse Recovery Time	t _{rr}	$T_J = 25$ °C, $I_F = I_S$	-	14	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	21	-	nC

Notes:

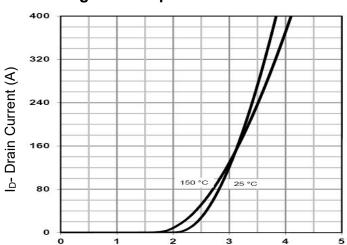
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=20V,VG=10V,L=0.5mH,Rg=25 Ω

Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

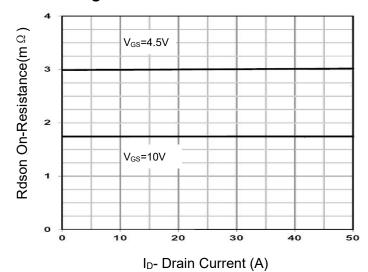
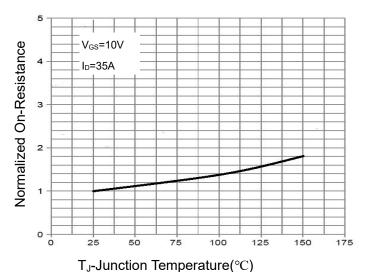


Figure 3 Rdson- Drain Current



13-3unction remperature(C)

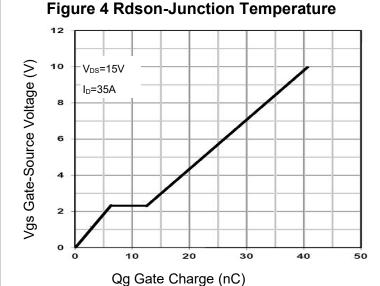
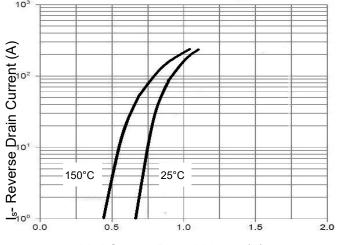
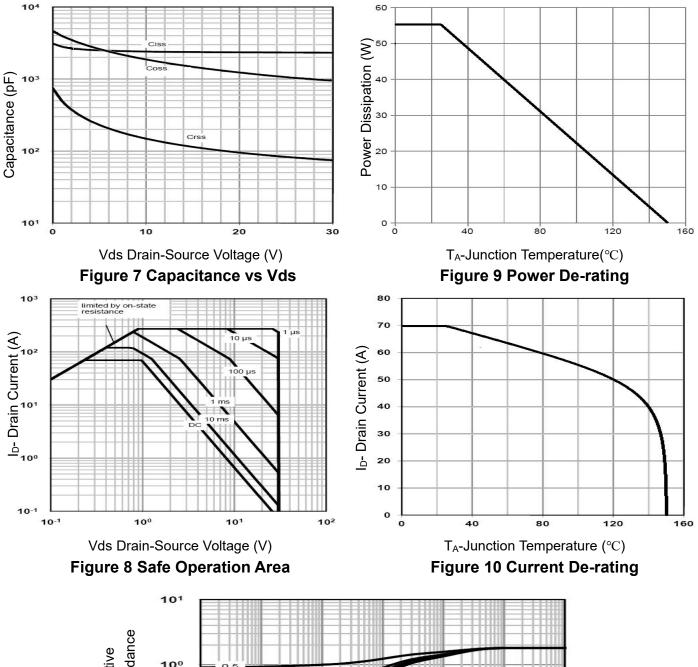


Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward



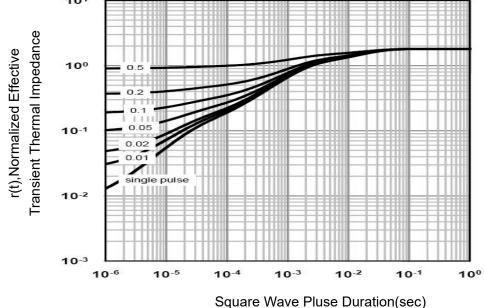
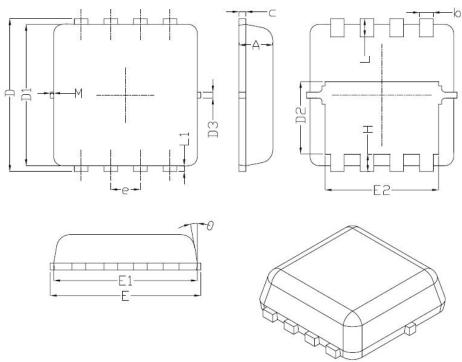
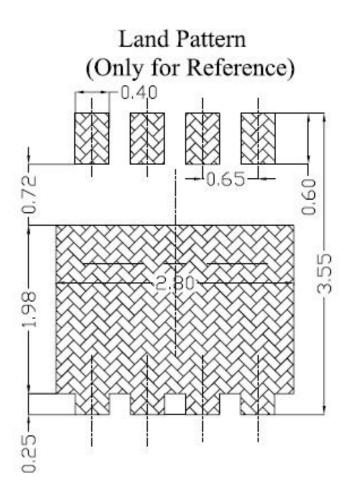


Figure 11 Normalized Maximum Transient Thermal Impedance

DFN3.3X3.3-8L Package Information



Symbol	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
A	0.70	0.75	0.80		
b	0.25	0.30	0.35		
С	0.10	0.15	0.25		
D	3.25	3.35	3.45		
D1	3.00	3.10	3.20		
D2	1.48	1.58	1.68		
D3	-	0.13	-		
E	3.20	3.30	3.40		
E1	3.00	3.15	3.20		
E2	2.39	2.49	2.59		
е	0.6	0.65BSC			
Н	0.30	0.39	0.50		
L	0.30	0.40	0.50		
L1	-	0.13	-		
M	*	*	0.15		
θ		10°	12 [°]		



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